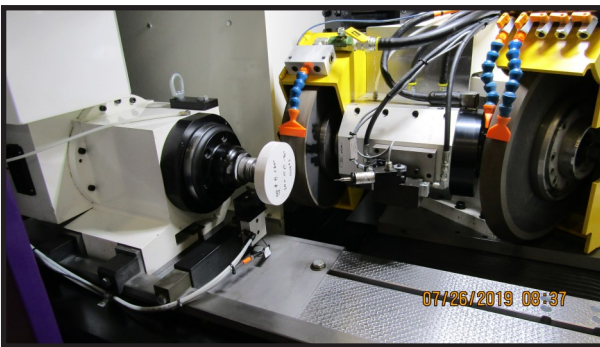
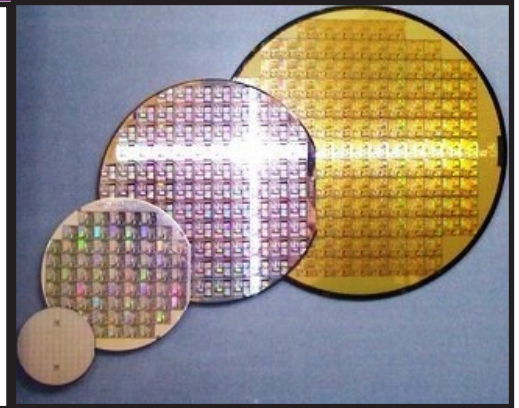


Midas 320A Dual Spindle SiC OD/Flat/Face Grinder

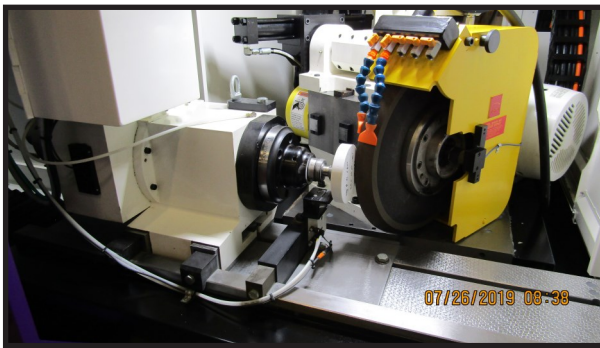


Silicon wafer production cost is greatly reduced with Weldon's unique multi-spindle design allowing OD, Flat, & Face grinding in the same operation.



A world leader in Silicon Wafer production came to Weldon for solutions to their unique SiC grinding requirements.

In this application an angular approach diamond grinding wheel is used to rough grind the OD & finish grind the end face. In the same operation, a sub-spindle with a straight approach diamond wheel is presented to finish grind the OD & generate one or two flats to specific C-axis coordinates. The results are increased productivity, lower production cost, & consistently high quality.



System Suppliers: **ATS** 5C collet chuck, **Setco** sub-spindle, **Spindel** frequency inverter, **Turmoil** spindle chiller, **Heidenhain** linear & rotary glass scales, & **FANUC** 32i BT CNC control.



Weldon Solutions offers a full line of CNC OD, ID, & combination grinders. As a FANUC Robotics integrator Weldon can also address your machine tending, material removal, material handling, & packaging/palletizing needs.

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